# ANDREW WOERPEL

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## PROFILE / OBJECTIVE

Highly motivated, hardworking, and technically diverse senior Electrical Engineering student with a desire to work on cutting edge and challenging projects that will have a great impact in the world.

## EDUCATION

**University of Wisconsin - Platteville**, Platteville, WI Anticipated Graduation: May 2017
College of Engineering, Mathematics, and Science
Major: Electrical Engineering, Emphasizing in Digital Electronics - GPA: 3.88/4.00
Minor: Computer Science

## RELEVANT COURSEWORK

| | | |
|---|---|---|
| Automatic Controls | Signals and Systems | Analog Electronics |
| Programming in C ++ | Logic and Digital Design | Circuit Modeling I & II |

## INTERNSHIP EXPERIENCE

**Orbital Technologies Corporation (ORBITEC)** Madison, WI Fall 2015 – Winter 2016 (Ongoing)
*Electrical Engineering Co-op*

- Developed cable assemblies, detailed subsystem test procedures, assembled/troubleshot hardware, and assisted with procurement for the next generation of micro-gravity greenhouses that will fly aboard the International Space Station in late 2016.
- Upgraded legacy greenhouse systems to match the Veggie unit which is currently demonstrating food production capabilities for astronauts on orbit.
- Assisted component librarian with component creation, schematic modification, and PCB layout in Altium.

**Plexus Corporation** Neenah, WI Summer 2015
*Software/Product Engineering Intern*

- Worked with a team to develop and maintained an 80,000 line C++ code base and corresponding test procedures for continuous integration/hardware-in-the-loop platforms on a large medical project.
- Developed a pneumatically actuated misuse test fixture for engineering confidence testing.

**Seljan Company** Lake Mills, WI Summer 2013 - Winter 2015
*Mechanical Design Intern*

- Established a batch powder coating system from the ground up. The total project cost was approximately $50,000.
- Suggested, designed, and constructed conveyor systems for metal stamping slug removal. System cost was approximately $2500 while equivalent commercially available systems cost in excess of $10,000.

## TECHNICAL / ENGINEERING SKILLS

- Laboratory experience with thin film deposition through thermal evaporation, reactive ion etching, scanning electron microscopy, and profilometers from undergraduate research in Microsystems & Nanotechnology
- Self-taught computer programming skills in Python, C++, and MATLAB
- Proficient in SOLIDWORKS 3D modeling software
- Experience designing, building, and troubleshooting basic data acquisition circuitry and software
- Excellent with hands on task such as fabrication and troubleshooting
- Experience with rapid prototyping using 3D printers

## MEMBERSHIPS / AFFILIATIONS

- Eagle Scout, Boy Scouts of America 2001 - 2012
- Pole Vaulter, UW – Platteville Track and Field Fall 2012 – Winter 2013
- Team Capitan, Society of Automotive Engineers - Aero Design Team Fall 2014 – Present
- Peer-Assisted Leader (Tutoring program for an entire class) Spring 2014
- Elec. & Software Team Lead, rLoop - SpaceX Hyperloop Design Competition Summer 2015 - Present